

ABSTRACT

The present invention aims to provide an adhesive sheet for back grinding capable of suppressing peeling of an adhesive layer and capable of peeling a wafer easily from an adhesive sheet.

According to the present invention, provided is an adhesive sheet for back grinding of a semiconductor wafer having a convex part, comprising: a base material layer; and an adhesive layer provided on the base material layer, wherein: the adhesive layer comprises an opening part having a diameter smaller than a diameter of the semiconductor wafer; the adhesive layer is adhered to an outer peripheral part of the semiconductor wafer so that the convex part of the semiconductor wafer is placed in the opening part; the adhesive layer is configured so that the convex part is protected by the base material layer with the semiconductor wafer adhered to the adhesive layer; the base material layer comprises a cushion layer and a surface treatment layer provided thereon; the adhesive layer is provided on the surface treatment layer; the surface treatment layer is formed of an acrylic resin composition containing an acrylic resin; the acrylic resin is cross-linked by light irradiation or heating; and the adhesive layer is formed of an acrylic resin composition containing an acrylic resin.

[Fig. 1]